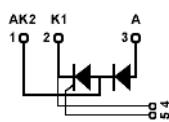


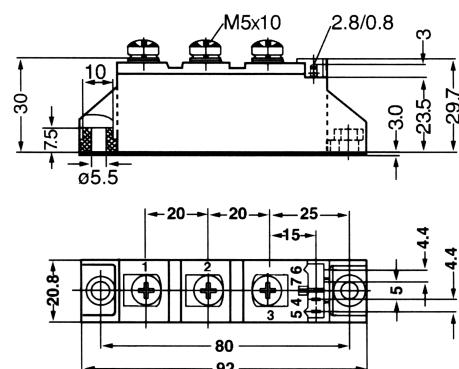
# STD/SDT116

## Thyristor-Diode Modules, Diode-Thyristor Modules



Type	$V_{RSM}$ $V_{DSM}$	$V_{RRM}$ $V_{DRM}$
	V	V
STD/SDT116GK08	900	800
STD/SDT116GK12	1300	1200
STD/SDT116GK14	1500	1400
STD/SDT116GK16	1700	1600
STD/SDT116GK18	1900	1800

Dimensions in mm (1mm=0.0394")



Symbol	Test Conditions	Maximum Ratings	Unit
$I_{TRMS}$ , $I_{FRMS}$ $I_{TAVM}$ , $I_{FAVM}$	$T_{VJ}=T_{VJM}$ $T_c=85^\circ C$ ; 180° sine	180 116	A
$I_{TSM}$ , $I_{FSM}$	$T_{VJ}=45^\circ C$ $V_R=0$	2250 2400	A
	$T_{VJ}=T_{VJM}$ $V_R=0$	2000 2150	
$\int i^2 dt$	$T_{VJ}=45^\circ C$ $V_R=0$	25300 23900	$A^2 s$
	$T_{VJ}=T_{VJM}$ $V_R=0$	20000 19100	
$(di/dt)_{cr}$	$T_{VJ}=T_{VJM}$ $f=50Hz$ , $t_p=200\mu s$ $V_D=2/3V_{DRM}$ $I_G=0.45A$	150	A/us
	non repetitive, $I_T=I_{TAVM}$ $dI/dt=0.45A/\mu s$	500	
$(dv/dt)_{cr}$	$T_{VJ}=T_{VJM}$ ; $V_{DR}=2/3V_{DRM}$ $R_{GK}=\infty$ ; method 1 (linear voltage rise)	1000	V/us
$P_{GM}$	$T_{VJ}=T_{VJM}$ $I_T=I_{TAVM}$	10 5	W
$P_{GAV}$		0.5	W
$V_{RGM}$		10	V
$T_{VJ}$ $T_{VJM}$ $T_{stg}$		-40...+125 125 -40...+125	°C
$V_{ISOL}$	50/60Hz, RMS $I_{ISOL}\leq 1mA$	3000 3600	V~
$M_d$	Mounting torque (M5) Terminal connection torque (M5)	2.5-4.0/22-35 2.5-4.0/22-35	Nm/lb.in.
<b>Weight</b>	Typical including screws	90	g

# STD/SDT116

## Thyristor-Diode Modules, Diode-Thyristor Modules

Symbol	Test Conditions	Characteristic Values	Unit
$I_{RRM}, I_{DRM}$	$T_{VJ}=T_{VJM}; V_R=V_{RRM}; V_D=V_{DRM}$	5	mA
$V_T, V_F$	$I_T, I_F=300A; T_{VJ}=25^\circ C$	1.5	V
$V_{TO}$	For power-loss calculations only ( $T_{VJ}=125^\circ C$ )	0.8	V
$r_T$		2.4	$m\Omega$
$V_{GT}$	$V_D=6V; T_{VJ}=25^\circ C$ $T_{VJ}=-40^\circ C$	2.5 2.6	V
$I_{GT}$	$V_D=6V; T_{VJ}=25^\circ C$ $T_{VJ}=-40^\circ C$	150 200	mA
$V_{GD}$	$T_{VJ}=T_{VJM}; V_D=2/3V_{DRM}$	0.2	V
$I_{GD}$		10	mA
$I_L$	$T_{VJ}=25^\circ C; t_p=10\mu s; V_D=6V$ $I_G=0.45A; dI/dt=0.45A/\mu s$	450	mA
$I_H$	$T_{VJ}=25^\circ C; V_D=6V; R_{GK}=\infty$	200	mA
$t_{gd}$	$T_{VJ}=25^\circ C; V_D=1/2V_{DRM}$ $I_G=0.45A; dI/dt=0.45A/\mu s$	2	us
$t_q$	$T_{VJ}=T_{VJM}; I_T=150A; t_p=200\mu s; -dI/dt=10A/\mu s$ $V_R=100V; dv/dt=20V/\mu s; V_D=2/3V_{DRM}$	typ. 185	us
$Q_s$	$T_{VJ}=T_{VJM}; I_T, I_F=50A; -dI/dt=6A/\mu s$	170	uC
$I_{RM}$		45	A
$R_{thJC}$	per thyristor/diode; DC current per module	0.22 0.11	K/W
$R_{thJK}$	per thyristor/diode; DC current per module	0.42 0.21	K/W
$ds$	Creeping distance on surface	12.7	mm
$da$	Strike distance through air	9.6	mm
$a$	Maximum allowable acceleration	50	$m/s^2$

### FEATURES

- \* International standard package
- \* Copper base plate
- \* Planar passivated chips
- \* Isolation voltage 3600 V~

### APPLICATIONS

- \* DC motor control
- \* Softstart AC motor controller
- \* Light, heat and temperature control

### ADVANTAGES

- \* Space and weight savings
- \* Simple mounting with two screws
- \* Improved temperature and power cycling
- \* Reduced protection circuits



# STD/SDT116

## Thyristor-Diode Modules, Diode-Thyristor Modules

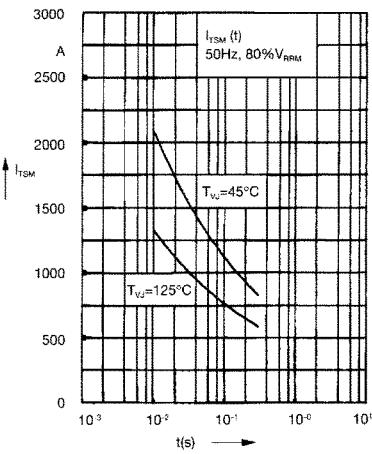


Fig. 1 Surge overload current  
 $I_{FSM}, I_{FDM}$ : Crest value, t: duration

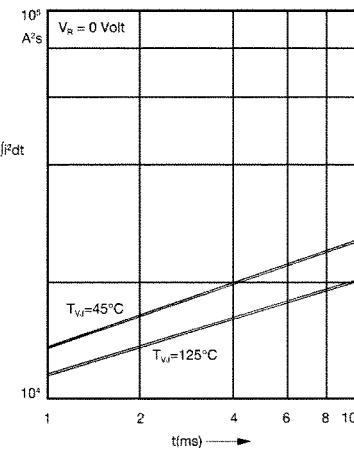


Fig. 2  $\int i^2 dt$  versus time (1-10 ms)

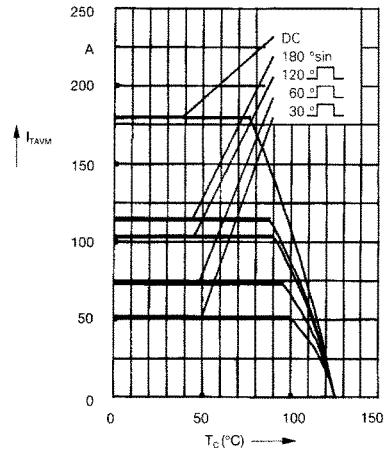


Fig. 2a Maximum forward current  
at case temperature

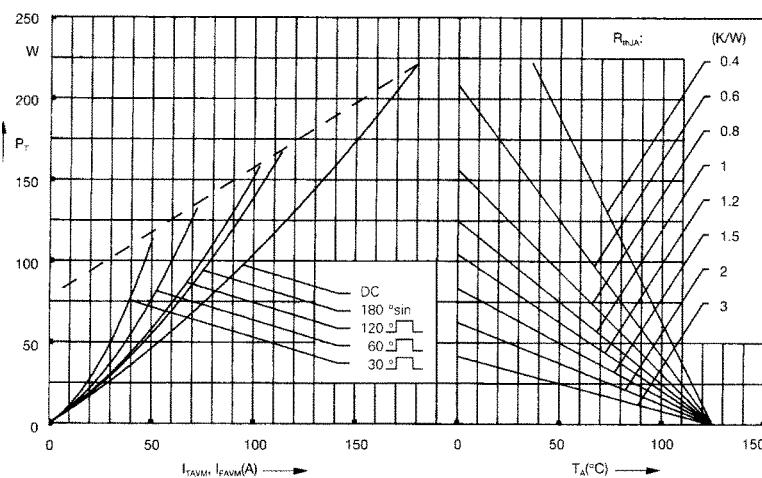


Fig. 3 Power dissipation versus on-state current and ambient temperature  
(per thyristor or diode)

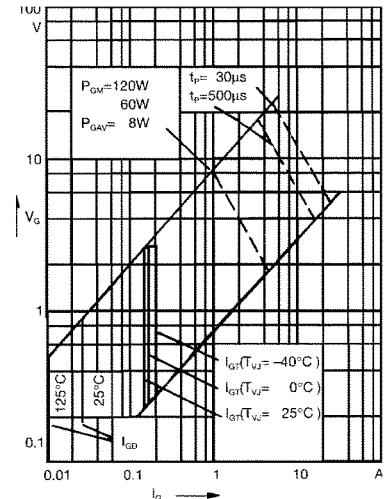


Fig. 4 Gate trigger characteristics

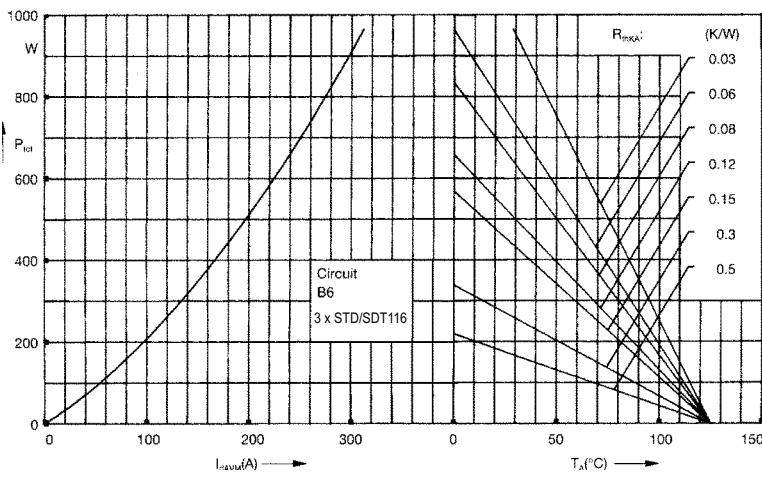


Fig. 5 Three phase rectifier bridge: Power dissipation versus direct output current  
and ambient temperature

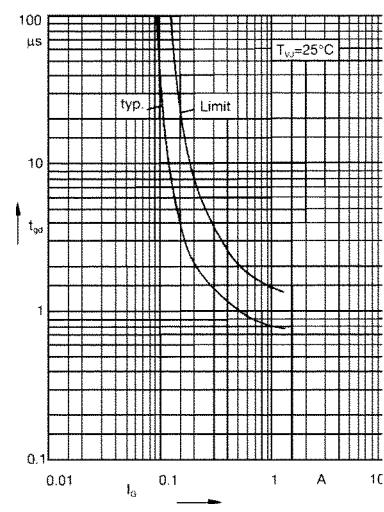


Fig. 6 Gate trigger delay time

# STD/SDT116

## Thyristor-Diode Modules, Diode-Thyristor Modules

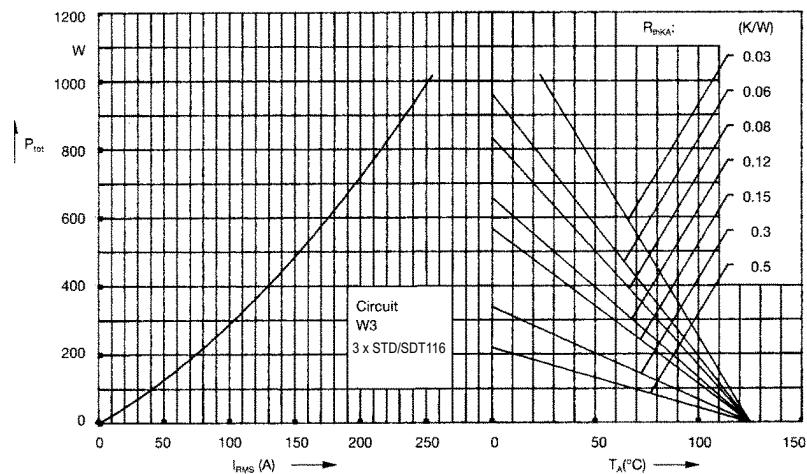


Fig. 7 Three phase AC-controller:  
Power dissipation versus RMS  
output current and ambient  
temperature

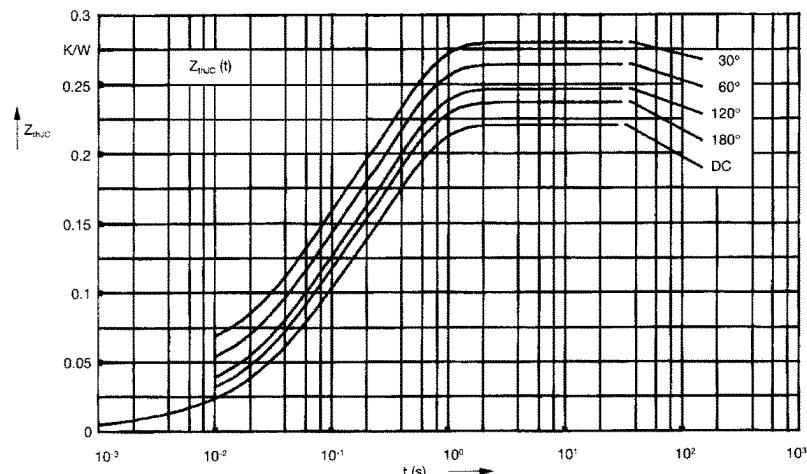


Fig. 8 Transient thermal impedance  
junction to case (per thyristor or  
diode)

$R_{thJC}$  for various conduction angles d:

d	$R_{thJC}$ (K/W)
DC	0.22
180°	0.23
120°	0.25
60°	0.27
30°	0.28

Constants for  $Z_{thJC}$  calculation:

i	$R_{thi}$ (K/W)	$t_i$ (s)
1	0.0066	0.0019
2	0.0678	0.0477
3	0.1456	0.344

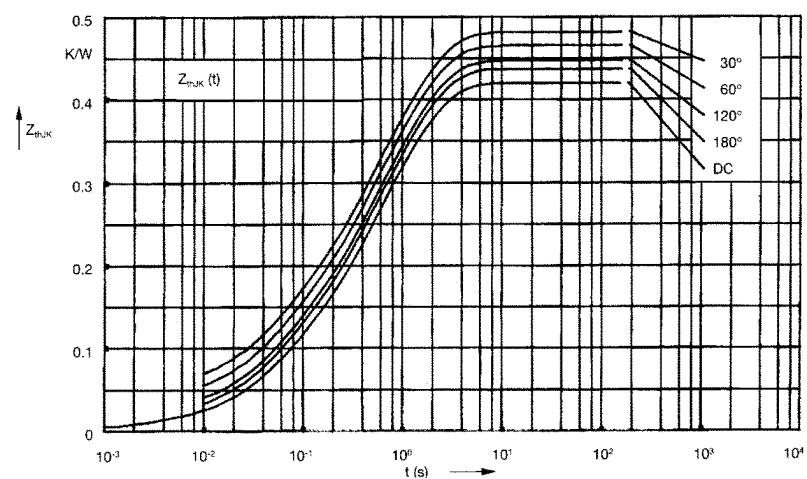


Fig. 9 Transient thermal impedance  
junction to heatsink (per thyristor or  
diode)

$R_{thJK}$  for various conduction angles d:

d	$R_{thJK}$ (K/W)
DC	0.42
180°	0.43
120°	0.45
60°	0.47
30°	0.48

Constants for  $Z_{thJK}$  calculation:

i	$R_{thi}$ (K/W)	$t_i$ (s)
1	0.0066	0.0019
2	0.0678	0.0477
3	0.1456	0.344
4	0.2	1.32